

SEMiX 353GB126HDs



SEMIX® 3s

Trench IGBT Modules

SEMiX 353GB126HDs

Preliminary Data

Features

- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability

Typical Applications

- AC inverter drives
- UPS
- Electronic Welding

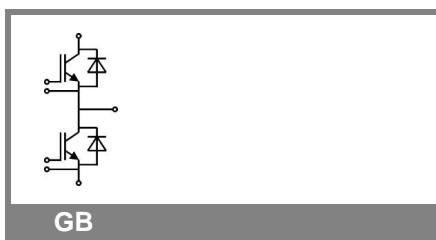
Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.

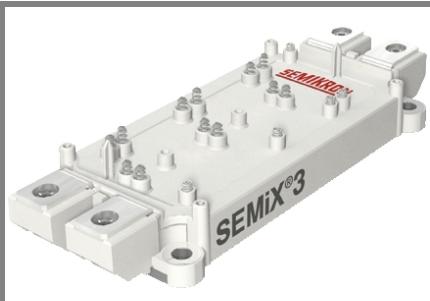
| Absolute Maximum Ratings | | $T_{case} = 25^\circ\text{C}$, unless otherwise specified | | |
|--------------------------|--|--|---|---------------|
| Symbol | Conditions | Values | | Units |
| IGBT | | | | |
| V_{CES} | $T_j = 25^\circ\text{C}$ | 1200 | | V |
| I_C | $T_j = 150^\circ\text{C}$ $T_c = 25^\circ\text{C}$ $T_c = 80^\circ\text{C}$ | 365 255 | A | A |
| I_{CRM} | $I_{CRM} = 2 \times I_{Cnom}$ | 450 | | A |
| V_{GES} | | ± 20 | | V |
| t_{psc} | $V_{CC} = 600\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125^\circ\text{C}$ $V_{CES} < 1200\text{ V}$ | 10 | | μs |

| | | | | |
|----------------------|---|----------------|---|------------------|
| Inverse Diode | | | | |
| I_F | $T_j = 150^\circ\text{C}$ $T_c = 25^\circ\text{C}$ $T_c = 80^\circ\text{C}$ | 330 225 | A | A |
| I_{FRM} | $I_{FRM} = 2 \times I_{Fnom}$ | 450 | | A |
| I_{FSM} | $t_p = 10\text{ ms; sin.}$ $T_j = 25^\circ\text{C}$ | 1700 | | A |
| Module | | | | |
| $I_{t(RMS)}$ | | 600 | A | |
| T_{vj} | | - 40 ... + 150 | | $^\circ\text{C}$ |
| T_{stg} | | - 40 ... + 125 | | $^\circ\text{C}$ |
| V_{isol} | AC, 1 min. | 4000 | | V |

| Characteristics | | $T_{case} = 25^\circ\text{C}$, unless otherwise specified | | |
|-------------------------------------|--|--|--------------------|------------------|
| Symbol | Conditions | min. | typ. | max. |
| IGBT | | | | |
| $V_{GE(th)}$ | $V_{GE} = V_{CE}, I_C = 9\text{ mA}$ | 5 | 5,8 | 6,5 |
| I_{CES} | $V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$ $T_j = 25^\circ\text{C}$ | | 0,3 | mA |
| V_{CEO} | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | 1 0,9 | 1,2 1,1 | V |
| r_{CE} | $V_{GE} = 15\text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | 3,1 4,9 | 4,2 6 | $\text{m}\Omega$ |
| $V_{CE(sat)}$ | $I_{Cnom} = 225\text{ A}, V_{GE} = 15\text{ V}$ $T_j = 25^\circ\text{C}_{\text{chiplev.}}$ $T_j = 125^\circ\text{C}_{\text{chiplev.}}$ | 1,7 2 | 2,1 2,4 | V |
| C_{ies} C_{oes} C_{res} | $V_{CE} = 25, V_{GE} = 0\text{ V}$ $f = 1\text{ MHz}$ | 16 0,84 0,73 | | nF |
| Q_G | $V_{GE} = -8 \dots +15\text{V}$ | 1800 | | nC |
| $t_{d(on)}$ t_r E_{on} | $R_{Gon} = 2\text{ }\Omega$ | $V_{CC} = 600\text{V}$ $I_{Cnom} = 225\text{A}$ | 265 55 26,5 | ns ns mJ |
| $t_{d(off)}$ t_f E_{off} | $R_{Goff} = 2\text{ }\Omega$ | $T_j = 125^\circ\text{C}$ | 585 120 32,5 | ns ns mJ |
| $R_{th(j-c)}$ | per IGBT | | 0,1 | K/W |



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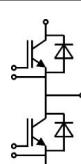
Remarks

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| Characteristics | | min. | typ. | max. | Units |
|-----------------------------------|---|---------------------------|---------------------|------------|---------------|
| Symbol | Conditions | | | | |
| Inverse Diode | | | | | |
| $V_F = V_{EC}$ | $I_{Fnom} = 225 \text{ A}; V_{GE} = 0 \text{ V}$ $T_j = 25^\circ\text{C}_{\text{chiplev.}}$ $T_j = 125^\circ\text{C}_{\text{chiplev.}}$ | | 1,6 1,6 | 1,8 1,8 | V V |
| V_{FO} | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | 1 0,8 | 1,1 0,9 | V V |
| r_F | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | 2,7 3,6 | 3,1 4 | mΩ mΩ |
| I_{RRM} Q_{rr} E_{rr} | $I_{Fnom} = 225 \text{ A}$ $di/dt = 5600 \text{ A}/\mu\text{s}$ $V_{GE} = -15 \text{ V}; V_{CC} = 600 \text{ V}$ | $T_j = 125^\circ\text{C}$ | 330 69 29 | | A μC mJ |
| $R_{th(j-c)D}$ | per diode | | | 0,17 | K/W |
| Module | | | | | |
| L_{CE} | | | 20 | | nH |
| $R_{CC'+EE'}$ | res., terminal-chip $T_{case} = 25^\circ\text{C}$ $T_{case} = 125^\circ\text{C}$ | | 0,7 1 | | mΩ mΩ |
| $R_{th(c-s)}$ | per module | | 0,04 | | K/W |
| M_s | to heat sink (M5) | | 3 | 5 | Nm |
| M_t | to terminals (M6) | | 2,5 | 5 | Nm |
| w | | | | 300 | g |
| Temperature sensor | | | | | |
| R_{100} $B_{100/125}$ | $T_c=100^\circ\text{C} (R_{25}=5 \text{ k}\Omega)$ $R(T)=R_{100}\exp[B_{100/125}(1/T-1/T_{100})];$ $T[\text{K}]; B$ | | 0,493±5% 3550±2% | | kΩ K |

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



GB

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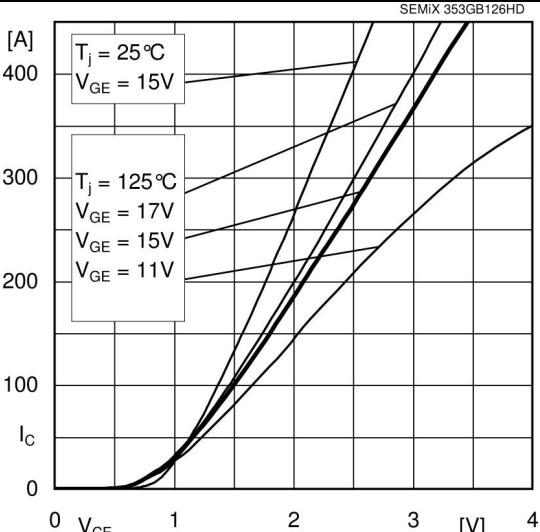


Fig. 1 Typ. output characteristic, inclusive $R_{CC} + EE'$

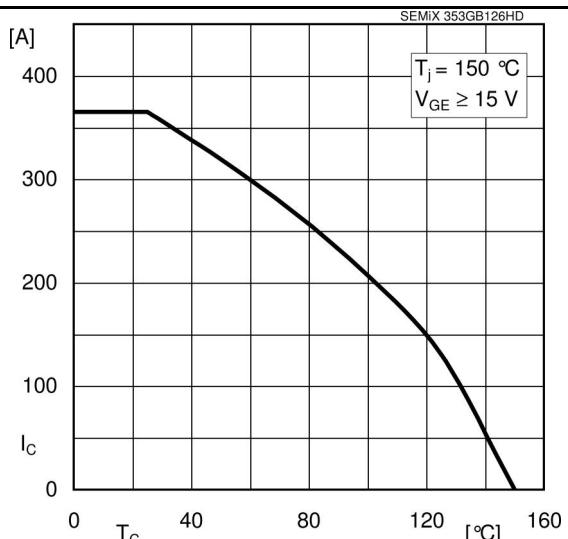


Fig. 2 Rated current vs. temperature $I_C = f(T_C)$

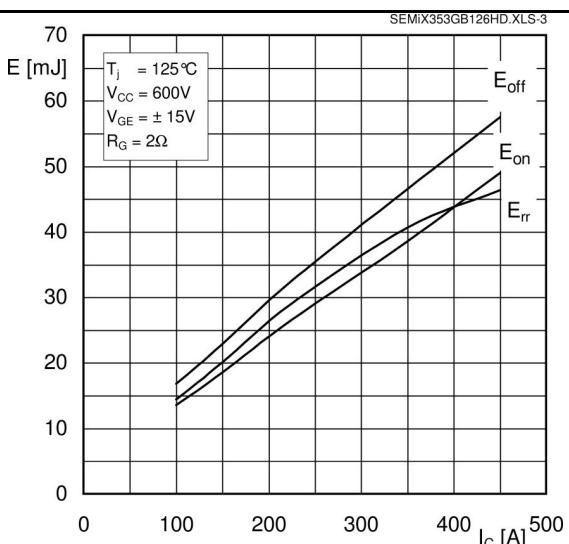


Fig. 3 Typ. turn-on /-off energy = f (I_C)

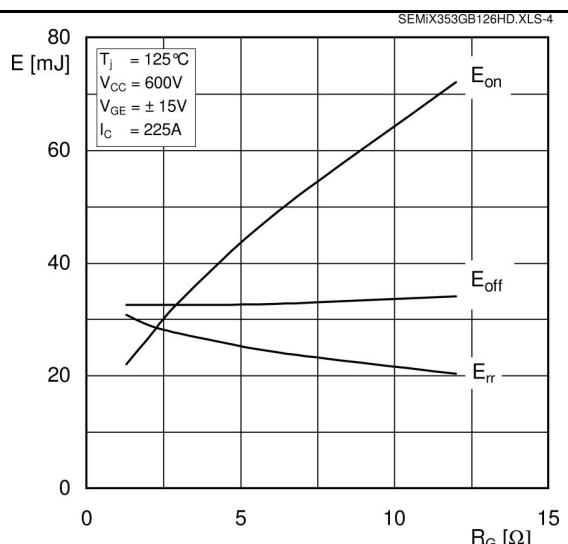


Fig. 4 Typ. turn-on /-off energy = f (R_G)

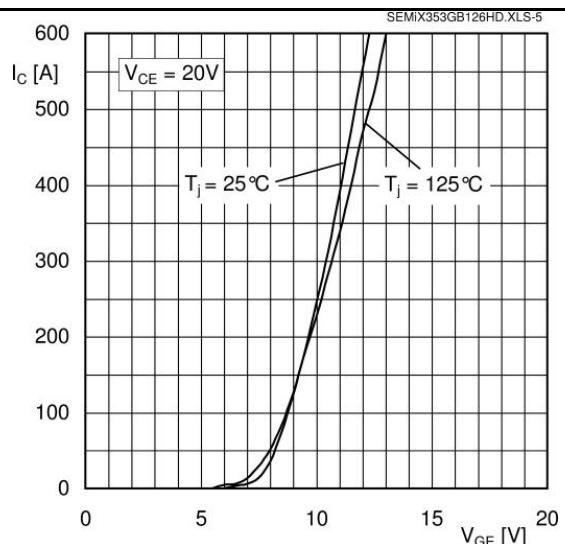


Fig. 5 Typ. transfer characteristic

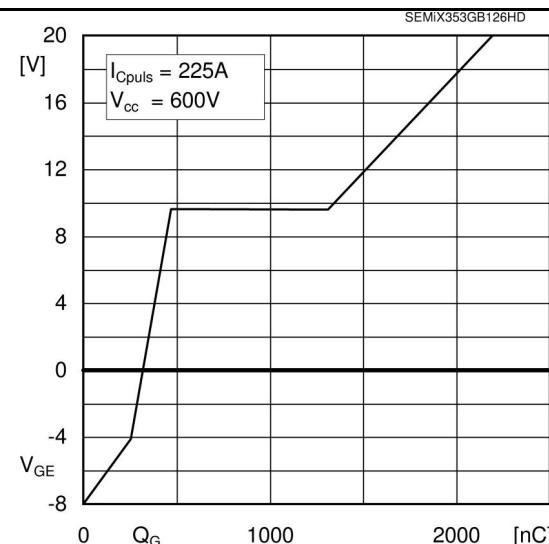


Fig. 6 Typ. gate charge characteristic

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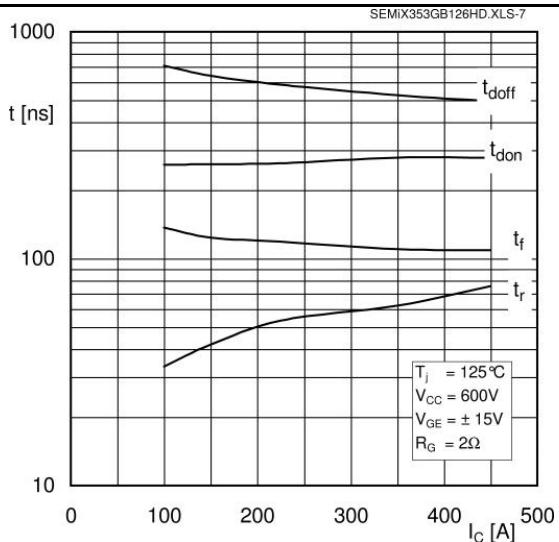


Fig. 7 Typ. switching times vs. I_c

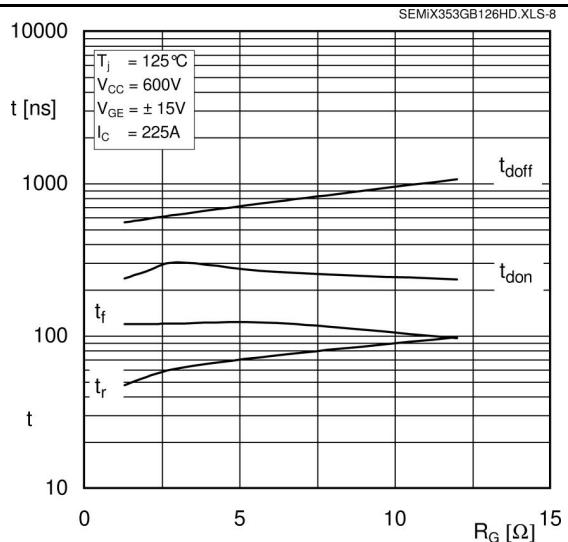


Fig. 8 Typ. switching times vs. gate resistor R_G

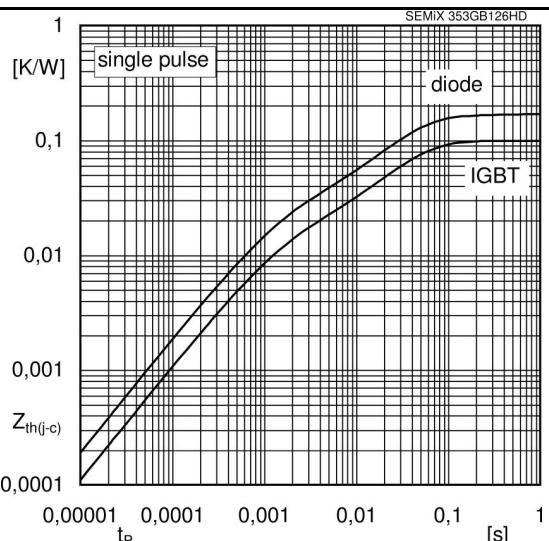


Fig. 9 Typ. transient thermal impedance

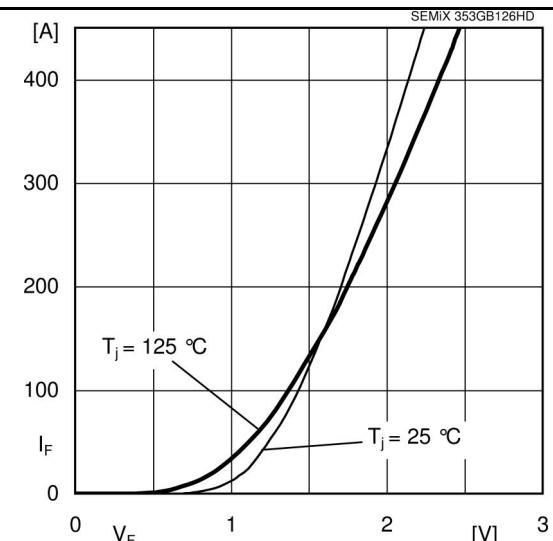


Fig. 10 Typ. CAL diode forward charact., incl. R_{CC+EE}

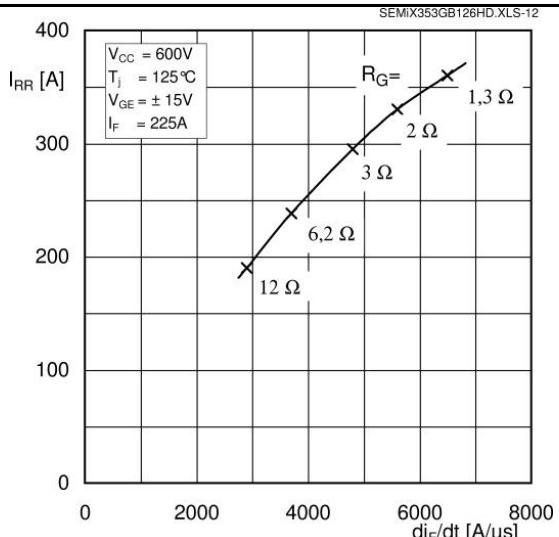


Fig. 11 Typ. CAL diode peak reverse recovery current

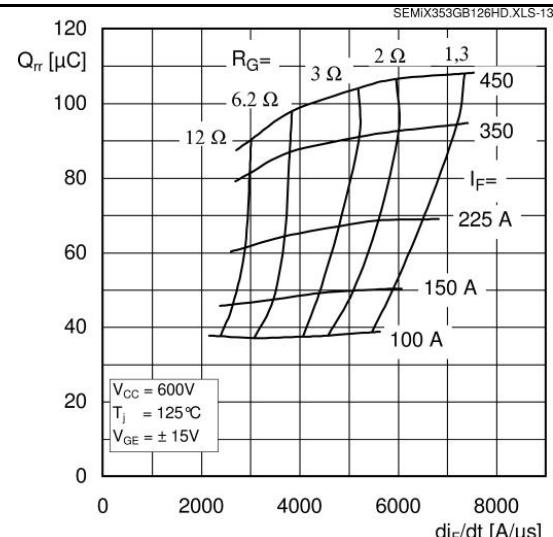
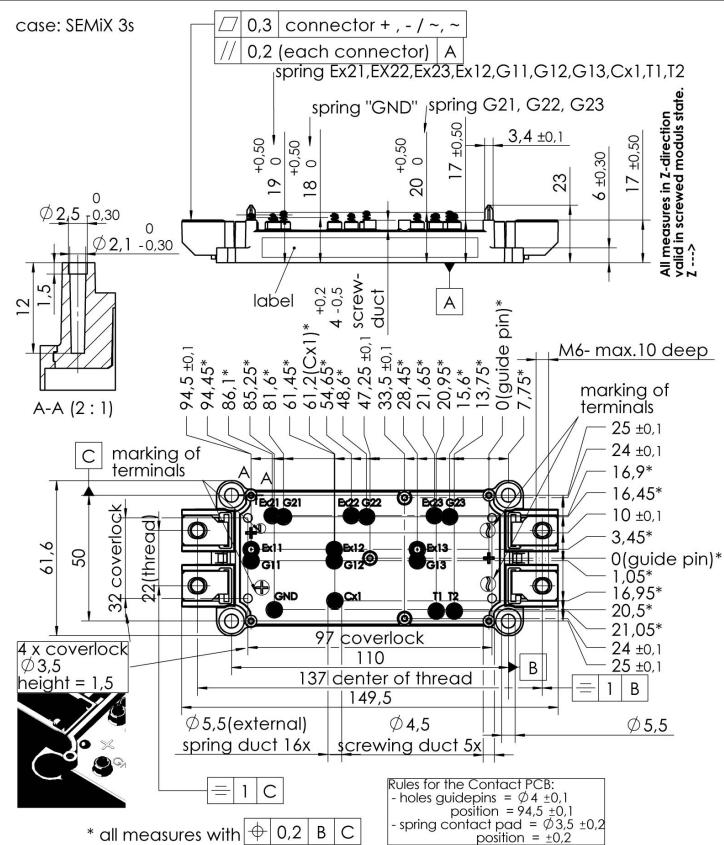


Fig. 12 Typ. CAL diode recovery charge

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Case SEMiX 3s

